

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention

THERMAL INTERFACE ADHESIVE AND REWORK

Application Number :

Confirmation Number:

First Named Applicant: Krishna Sachdev

Attorney Docket Number: FIS920030420US1

Art Unit:

Examiner:

Search string: (6118177 or 5853888 or 4649992 or 6548175 or 6652665 or 20030067069 or 20030068487 or 20030041442 or 20020143092).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6118177	2000-09-12	Lischner et al.			
	2	5853888	1998-12-29	Dutta et al			
	3	4649992	1987-03-17	Geen et al			
	4	6548175	2003-04-15	Sachdev et al			
	5	6652665	2003-11-25	Sachdev et al			

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030067069	2003-04-10	Lebonheur et al			
	2	20030068487	2003-04-10	Nguyen et al			
	3	20030041442	2003-03-06	McCullough			
	4	20020143092	2002-10-03	Matayabas, Jr.			

Signature

Examiner Name	Date